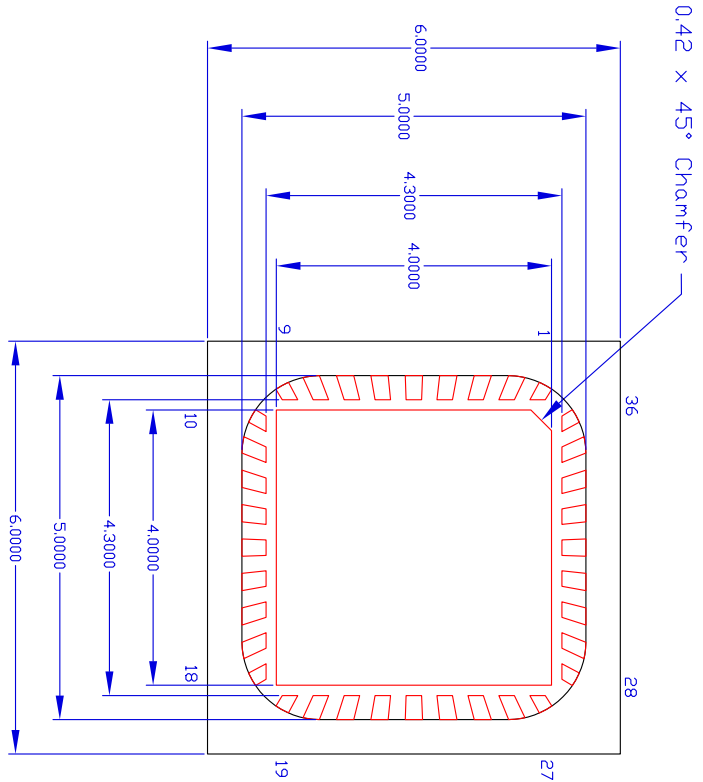
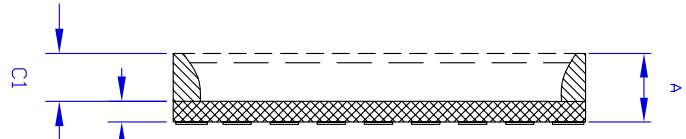


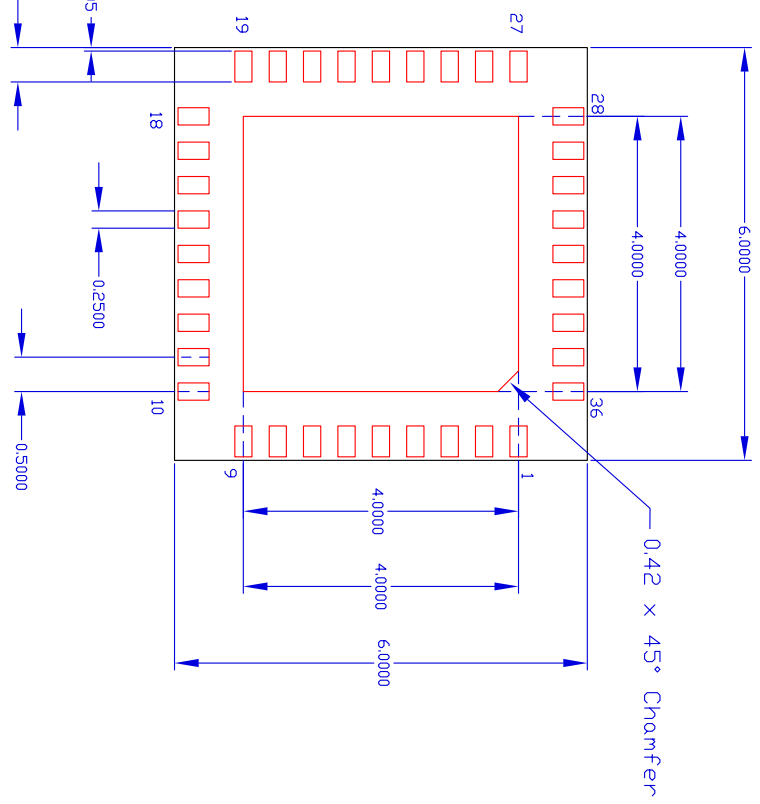
TOP VIEW



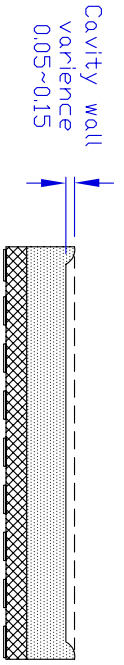
SIDE VIEW



BOTTOM VIEW



SIDE VIEW



| HEIGHT TABLE | | | |
|--------------|----------|----------|----------|
| SERIES | C1 | C2 | A |
| A-QFN | 0.63 | 0.27 | 0.90 |
| A-TQFN | 0.38 | 0.27 | 0.65 |
| TOL | +/- 0.10 | +/- 0.05 | +/- 0.15 |

OTHER SIZES AVAILABLE

Note:

- Organic substrate
- Cavity Dam: Hysol FP4451TD
- Pads: Cu/Ni/Au
- Copper Thickness: 12µm~18µm (0.5~0.7mil)
- Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
- PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
- Nickel Thickness: 38µm (150 micro-inch)
- All Dimensions Are mm

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| | | | | | |
|--|------|-------------|-------|----------|------|
| TOLERANCES UNLESS NOTED: | | APPROVALS | | DATE | |
| X.XX | ± | DRAWN TA | | 11/29/08 | |
| X.XXX | ± | | | | |
| X.XXXX | ± | | | | |
| ALL DIMENSIONS ARE IN: <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS | | ENG | | | |
| THIRD ANGLE PROJECTION: | | QA | | | |
| | | CUST | | | |
| | | REVISED | | | |
| <p style="text-align: center;"> </p> | | | | | |
| TITLE 36-LEAD 6MM P=0.50MM | | | | | |
| A-QFN (AIR) OPEN CAVITY | | | | | |
| SCALE | SIZE | DRAWING NO. | REV | | |
| NONE | A | 453610 | A | | |
| DO NOT SCALE DRAWING | | | SHEET | 1 | OF 1 |